

APPROVAL SHEET

RF Switch Series – RoHS Compliance

SP4T GPIO Switch

Halogens Free Product

Any 2G/3G/4G Band for TRx System

P/N: RFASWK694CTF09

FEATURES

■ Low Insertion Loss and Low Distortion

■ Broadband frequency range: 0.5 to 2.7 GHz

■ Low ON-state resistance and OFF-state capacitance

■ High power and peak voltage handling

■ Low control voltage: 1.3V to 2.7V

■ High ESD tolerance of 2kV HBM at all pins

■ Miniature footprint: 1.1 x 1.5 x 0.45 mm³ (QFN 10-Pin)

■ <u>M</u>oisture <u>Sensitive</u> <u>Level 3 (MSL3)</u>

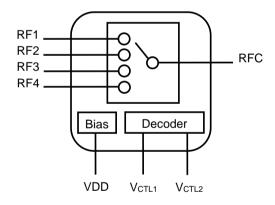
Description

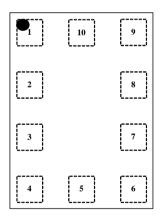
- The RFASWK694CTF09 is a Single-Pole, Four-Throw (SP4T) switch designed for antenna tuning applications that require very low RoN and Coff. The RFASWK694CTF09 provides rugged power handling and simple 2-bit GPIO control.
- The RFASWK694CTF09 features very low DC power consumption.

Application

- Antenna Tuning
- Band Switching
- Impedance Tuning

Block Diagram and Pin Out (Top View)

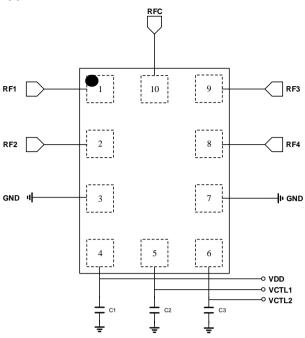




Pin Names and Descriptions

Pin	Name	Description	Pin	Name	Description
1	RF1	RF path 1	6	V _{CTL2}	DC control voltage 2
2	RF2	RF path 2	7	GND	Ground
3	GND	Ground	8	RF4	RF path 4
4	VDD	DC power supply	9	RF3	RF path 3
5	V _{CTL1}	DC control voltage 1	10	RFC	RF common port

Application Circuit



Parts List

Parts No.	Value
C1~C3	0.1uF

Absolute Maximum Ratings

Parameter	Symbol	Minimum	Maximum	Units
RFx Input Power, 50Ω	Pin		+40	dBm
DC Supply Voltage	VDD		+5.0	V
DC Control Voltage	Vctl		+3.3	V
Max differential RF voltage between the RF ports V _{RF}	VP		32	V
Storage temperature	T _{STG}	-55	+150	°C
Operating temperature	T _{OP}	-40	+85	°C
HBM ESD Voltage, All Pins	V _{ESD} ¹	-	+2000	V

Note 1: Human Body Model ESD Voltage

Exceeding absolute maximum ratings may cause permanent damage. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.



Electrical Specifications

(Top= 25°C, VDD=2.85V, V_{CTL}=0/1.8V, Characteristic Impedance Z0= 50 Ω, Unless Otherwise Noted)

Parameter Symbol		Test Condition	Min.	Тур.	Max.	Units
RF Specifications	•					
Operating Frequency	f		500		2700	MHz
Insertion Loss (RFC to RFx port)	IL	615 ~700 MHz 700 ~915 MHz 915 ~1910 MHz 1910~2700 MHz		0.30 0.38 0.58 0.67	0.35 0.48 0.75 1.00	dB dB dB
Isolation (RFC to RFx port)	Iso	615 ~700 MHz 700 ~915 MHz 915 ~1910 MHz 1910~2700 MHz	22 20 18 16	24 22 20 18		dB dB dB
Return Loss (RFC) Logic States 1, 2, 3, 4	VSWR	700 MHz 915 MHz 1910 MHZ		1.29 1.43 1.58	1.50 1.58 1.78	
	2 _{f0}	PIN = +23dBm, f = 700MHz PIN = +35dBm, f = 915MHz PIN = +33dBm, f = 1910MHz PIN = +23dBm, f = 2570MHz		-82 -60 -60 -70		dBm dBm dBm dBm
RFx Harmonics	3 _{f0}	PIN = +23dBm, f = 700MHz PIN = +35dBm, f = 915MHz PIN = +33dBm, f = 1910MHz PIN = +23dBm, f = 2570MHz		-98 -60 -70 -85		dBm dBm dBm dBm
2nd Order Input Intercept Point	IIP2	See IIP2 test conditions Table		120		dBm
3rd Order Input Intercept Point	IIP3	See IIP3 test conditions Table		75		dBm
RON (RFC to RF1/RF2/RF3/RF4) Logic States 1, 2, 3,4	Ron			1.2		Ω
COFF (RFC to RF1/RF2/RF3/RF4) Logic States 1, 2, 3,4	Coff			0.15		pF
DC Specification (Decoder)	•			l .		
Supply Voltage	V _{DD}		2.5	2.85	4.5	V
Supply Current	I _{DD}			55		μΑ
Control Voltage(High)	V _{CTL(H)}		1.3	1.8	2.7	V
Control Voltage(Low)	V _{CTL(L)}		0	0	0.45	V
Control Current	ICTL	V _{CTL} = 1.8V		2		μA
Switching Specification						
Start-up time	T _{ON}	50% VDD to large signal fully compliant		10		μs
On switching speed	Tsw	50% V _{CTL} to 90% RF On		5		μs
Off switching speed	Tsw	50% V _{CTL} to 90% RF Off		5		μs

Note: All measurements are made in a 50Ω system with 0/+1.8V control voltages, unless otherwise specified.



IIP2 Test Conditions

Band	In-Band Freq (MHz)	CW tone 1 (MHz)	CW tone 1 (dBm)	CW tone 2 (MHz)	CW tone 2 (dBm)
1	2140.0	1950.0	+20	190.0	–15
'	2140.0	1950.0	+26	4090.0	-20
2	1000.0	1880.0	+20	80.0	–15
2	2 1960.0		+26	3840.0	-20
5	881.5	926 F	+20	45.0	–15
5	5 661.5	836.5	+26	1718.0	-20
0	0 040.5	207.5	+20	45.0	-15
8	942.5	897.5	+26	1840.0	-20

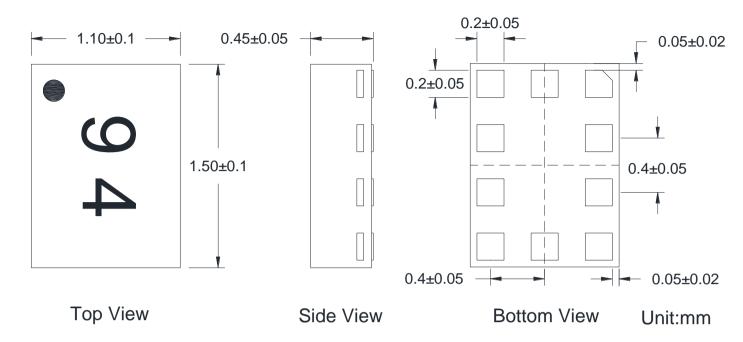
IIP3 Test Conditions

Band	In-Band Freq (MHz)	CW tone 1 (MHz)	CW tone 1 (dBm)	CW tone 2 (MHz)	CW tone 2 (dBm)
1	2140.0	1950.0	+20	1760.0	–15
2	1960.0	1880.0	+20	1800.0	–15
5	881.5	836.5	+20	791.5	-15
8	942.5	897.5	+20	852.5	–15

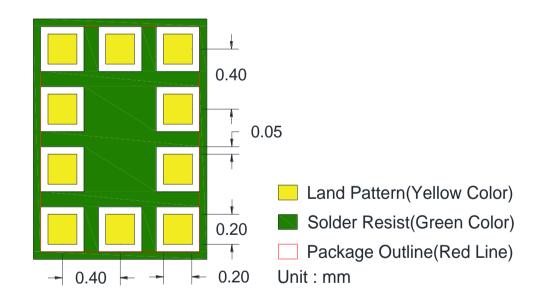
Logic Table for Switch On-Path (High=1.8V ,Low= 0V)

V _{CTL1}	V _{CTL2}	RF1	RF2	RF3	RF4
0	0	on	off	off	off
0	1	off	on	off	off
1	0	off	off	on	off
1	1	off	off	off	on
X	Х	Low Power Mode			

Package Dimensions



Land Pattern



Reliability test

TEST	PROCEDURE / TEST METHOD	REQUIREMENT	
Solderability	*Solder bath temperature: 255 ± 5°C	At least 95% of a surface of each terminal	
JIS C 0050-4.6	*Immersion time : 5 ± 0.5 sec	electrode must be covered by fresh solder.	
JESD22-B102D	Solder : Sn3Ag0.5Cu for lead-free		
High temperature	*Temperature : 90°C±2°C	No mechanical damage.	
JIS C 0021	*Test duration: 1000+24/-0 hours	Electrical specification shall satisfy the	
	Measurement to be made after keeping at room	descriptions in electrical characteristics under	
	temperature for 24±2 hrs	the operational temperature range within -30 ~	
		90°C.	
Low temperature	*Temperature : -30°C±2°C	No mechanical damage.	
JIS C 0020	*Test duration: 1000+24/-0 hours	Electrical specification shall satisfy the	
	Measurement to be made after keeping at room	descriptions in electrical characteristics under	
	temperature for 24±2 hrs	the operational temperature range within -30 ~	
	·	90°C.	
Temperature cycle	1. 30±3 minutes at -30±3°C,	No mechanical damage.	
JIS C 0025	2. 10~15 minutes at room temperature,	Electrical specification shall satisfy the	
	3. 30±3 minutes at +90±3°C,	descriptions in electrical characteristics under	
	4. 10~15 minutes at room temperature,	the operational temperature range within -30 ~	
	Total 100 continuous cycles	90°C.	
	Measurement to be made after keeping at room		
	temperature for 24±2 hrs		
High temperature operation	*Temperature : 90°C	No mechanical damage.	
life (HTOL)	*V = Vmax	Electrical specification shall satisfy the	
	*Time: 1000+24/-0 hrs.	descriptions in electrical characteristics under	
	Measurement to be made after keeping at room	the operational temperature range within -30 ~	
	temperature for 24±2 hrs	90°C.	

Soldering condition

Typical examples of soldering processes that provide reliable joints without any damage are given in Figure 11.

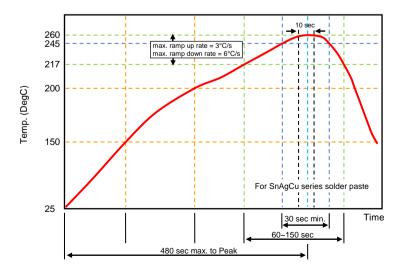


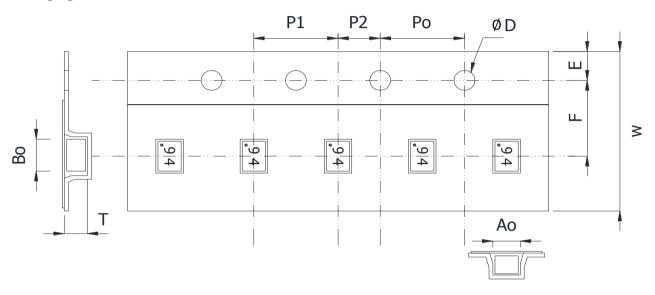
Figure 11. Infrared soldering profile

Ordering code

RF	ASW	к	694C	Т
RF module	Module type	Application	Design Code	Packing
RF:	ASW: Antenna Switch	K: SP4T		T: Taping
Walsin RF Switch Device				

Minimum Ordering Quantity: 3000 pcs per reel.

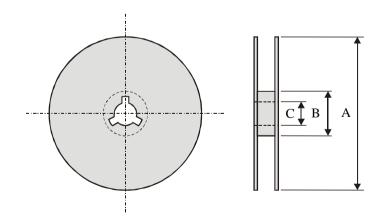
Packaging



Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.30 ± 0.05	1.70 ± 0.05	1.55 ± 0.05	0.60 ± 0.05	8.0 ± 0.20
Index	E	F	Ро	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.05	4.00 ± 0.05	2.00 ± 0.05

Reel dimensions



Index	А	В	С
Dimension (mm)	Ф178.0	Ф54.0	Ф13.2

Taping Quantity: 3000 pieces per 7" reel

Approval Sheet



Caution of handling

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.